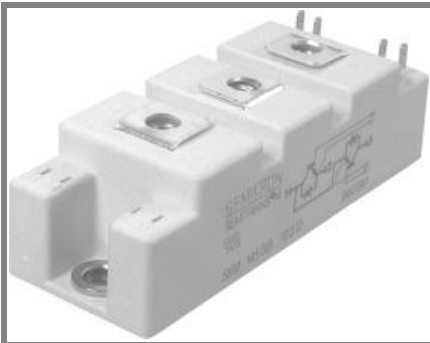


SKM 100GB12T4



SEMITRANS® 2

IGBT4 Modules

SKM 100GB12T4

Target Data

Features

- IGBT4 = 4. Generation (Trench) IGBT
- V_{CEsat} with positive temperature coefficient
- High short circuit capability, self limiting to $6 \times I_{CNOM}$
- Soft switching 4. generation CAL diode (CAL4)

Typical Applications

- AC inverter drives
- UPS
- Electronic welders at f_{sw} up to 20 kHz

Remarks

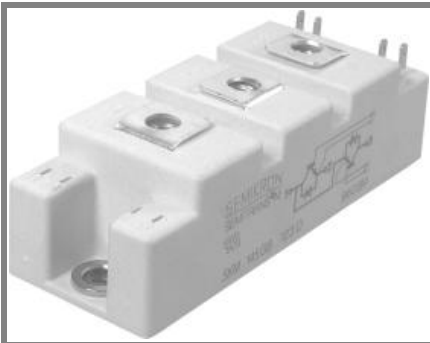
- Case temperature limited to $T_c = 125^\circ\text{C}$ max, recomm. $T_{op} = -40 \dots +150^\circ\text{C}$, product rel. results valid for $T_j \leq 150^\circ$



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Absolute Maximum Ratings		$T_c = 25^\circ\text{C}$, unless otherwise specified			
Symbol	Conditions	Values		Units	
IGBT					
V_{CES}	$T_j = 25^\circ\text{C}$	1200		V	
I_C	$T_j = 175^\circ\text{C}$	$T_{case} = 25^\circ\text{C}$	160		A
		$T_{case} = 80^\circ\text{C}$	125		A
I_{CRM}	$I_{CRM} = 3 \times I_{CNOM}$	300		A	
V_{GES}		± 20		V	
t_{psc}	$V_{CC} = 600\text{ V}; V_{GE} \leq 15\text{ V}; T_j = 150^\circ\text{C}$ $V_{CES} < 1200\text{ V}$	10		μs	
Inverse Diode					
I_F	$T_j = 175^\circ\text{C}$	$T_{case} = 25^\circ\text{C}$	120		A
		$T_{case} = 80^\circ\text{C}$	90		A
I_{FRM}	$I_{FRM} = 3 \times I_{FNOM}$	300		A	
I_{FSM}	$t_p = 10\text{ ms}; \text{sin.}$	$T_j = 175^\circ\text{C}$	550		A
Module					
$I_{t(RMS)}$		200		A	
T_{vj}		-40 ... +175		$^\circ\text{C}$	
T_{stg}		-40 ... +125		$^\circ\text{C}$	
V_{isol}	AC, 1 min.	4000		V	

Characteristics		$T_c = 25^\circ\text{C}$, unless otherwise specified				
Symbol	Conditions	min.	typ.	max.	Units	
IGBT						
$V_{GE(th)}$	$V_{GE} = V_{CE}, I_C = 4\text{ mA}$	5	5,8	6,5	V	
I_{CES}	$V_{GE} = V, V_{CE} = V_{CES}$				$T_j = 25^\circ\text{C}$ $T_j = 150^\circ\text{C}$ mA	
V_{CE0}			0,8	0,9	V	
					$T_j = 150^\circ\text{C}$	0,7
r_{CE}	$V_{GE} = 15\text{ V}$	$T_j = 25^\circ\text{C}$	10		11	$\text{m}\Omega$
		$T_j = 150^\circ\text{C}$	15		16	$\text{m}\Omega$
$V_{CE(sat)}$	$I_{Cnom} = 100\text{ A}, V_{GE} = 15\text{ V}$	$T_j = 25^\circ\text{C}_{chiplev.}$	1,8		2	V
		$T_j = 150^\circ\text{C}_{chiplev.}$	2,2		2,4	V
C_{res}	$V_{CE} = 25, V_{GE} = 0\text{ V}$	$f = 1\text{ MHz}$	6,2		nF	
C_{oes}			0,41		nF	
C_{res}			0,35		nF	
Q_G	$V_{GE} = -8\text{V}/+15\text{V}$		570		nC	
R_{Gint}	$T_j = 25^\circ\text{C}$		7,5		Ω	
$t_{d(on)}$	$R_{Gon} =$	$V_{CC} = 600\text{V}$ $I_{Cnom} = 100\text{A}$ $T_j = 150^\circ\text{C}$			ns	
t_r					ns	
E_{on}			11		mJ	
$t_{d(off)}$	$R_{Goff} =$				ns	
t_f					ns	
E_{off}			11		mJ	
$R_{th(j-c)}$	per IGBT		0,27		K/W	



SEMITRANS® 2

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Typical Applications

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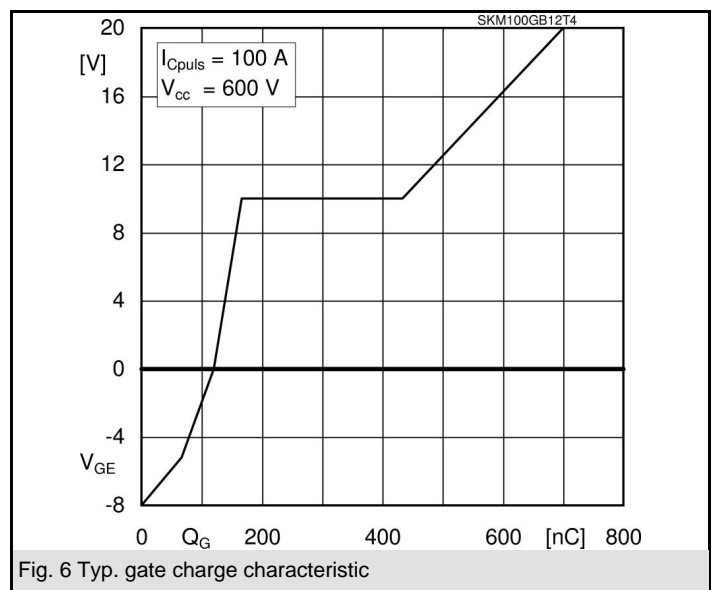
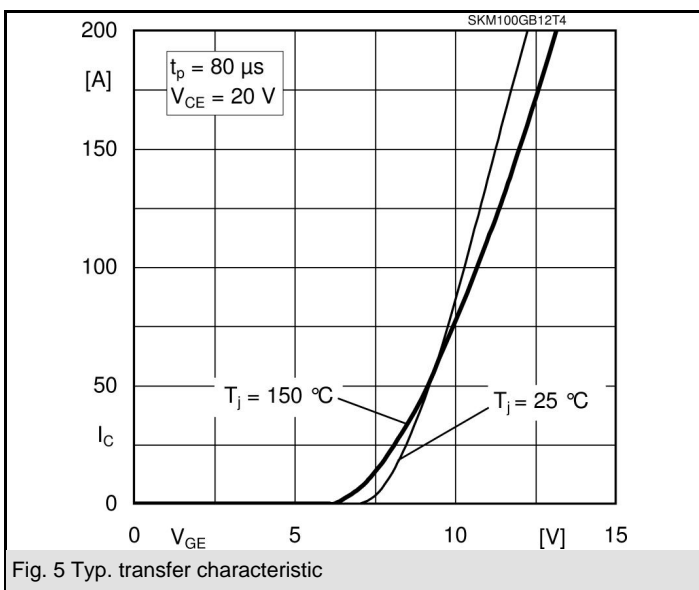
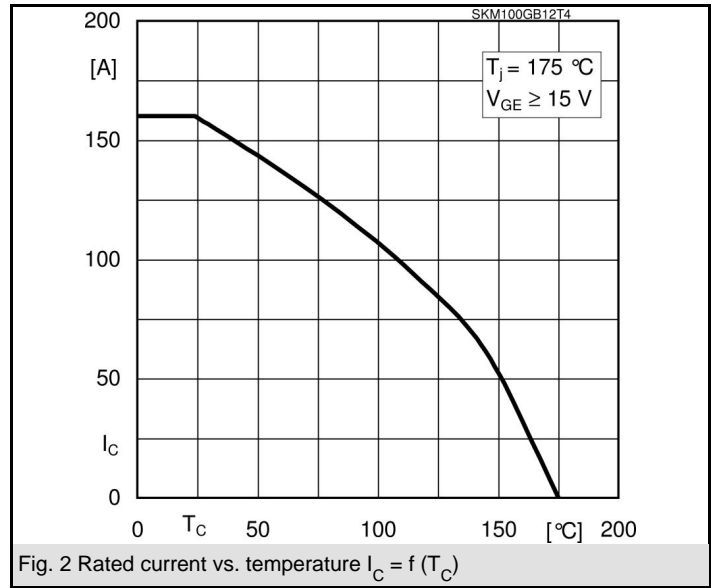
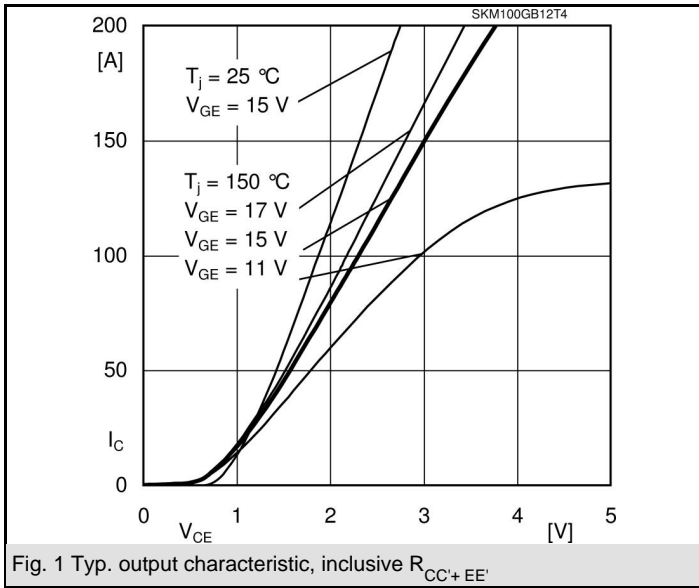


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Characteristics			min.	typ.	max.	Units
Symbol	Conditions					
Inverse Diode						
$V_F = V_{EC}$	$I_{Fnom} = 100 \text{ A}; V_{GE} = 0 \text{ V}$	$T_j = 25^\circ\text{C}_{chiplev.}$		2,2	2,5	V
		$T_j = 150^\circ\text{C}_{chiplev.}$		2,1	2,45	V
V_{F0}		$T_j = 25^\circ\text{C}$		1,3	1,5	V
		$T_j = 150^\circ\text{C}$		0,9	1,1	V
r_F		$T_j = 25^\circ\text{C}$		9	11	mΩ
		$T_j = 150^\circ\text{C}$		12	13,5	mΩ
I_{RRM}	$I_{Fnom} = 100 \text{ A}$	$T_j = 150^\circ\text{C}$				A
Q_{rr}						μC
E_{rr}	$V_{GE} \leq -8\text{V}$			7,5		mJ
$R_{th(j-c)}$	per diode				0,48	K/W
Freewheeling Diode						
$V_F = V_{EC}$	$I_{Fnom} = \text{A}; V_{GE} = \text{V}$	$T_j = ^\circ\text{C}_{chiplev.}$				V
V_{F0}		$T_j = ^\circ\text{C}$				V
r_F		$T_j = ^\circ\text{C}$				V
I_{RRM}	$I_{Fnom} = \text{A}$	$T_j = ^\circ\text{C}$				A
Q_{rr}						μC
E_{rr}						mJ
	per diode					K/W
Module						
L_{CE}				20	30	nH
$R_{CC'+EE'}$	res., terminal-chip	$T_{case} = 25^\circ\text{C}$			0,75	mΩ
		$T_{case} = 125^\circ\text{C}$			1	mΩ
$R_{th(c-s)}$	per module				0,05	K/W
M_s	to heat sink M6			3	5	Nm
M_t	to terminals M5			2,5	5	Nm
w					160	g

This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, Chapter IX.

This technical information specifies semiconductor devices but promises no characteristics. No warranty or guarantee expressed or implied is made regarding delivery, performance or suitability.



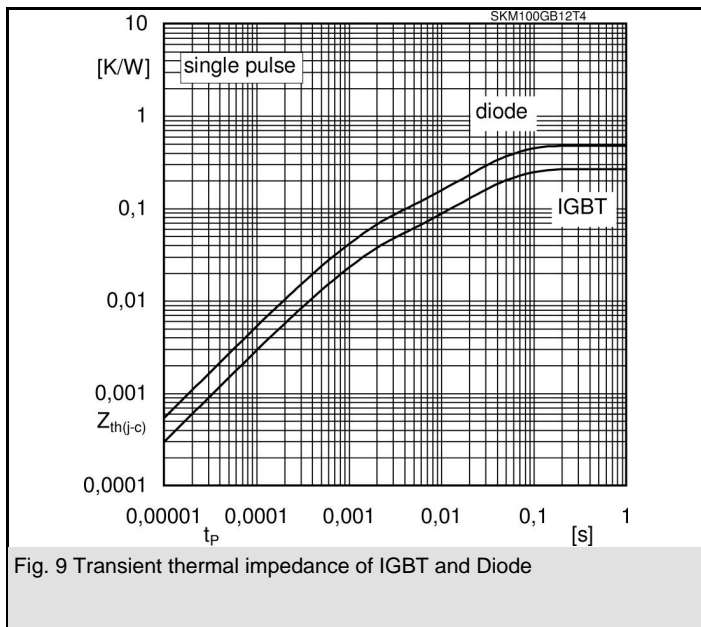


Fig. 9 Transient thermal impedance of IGBT and Diode

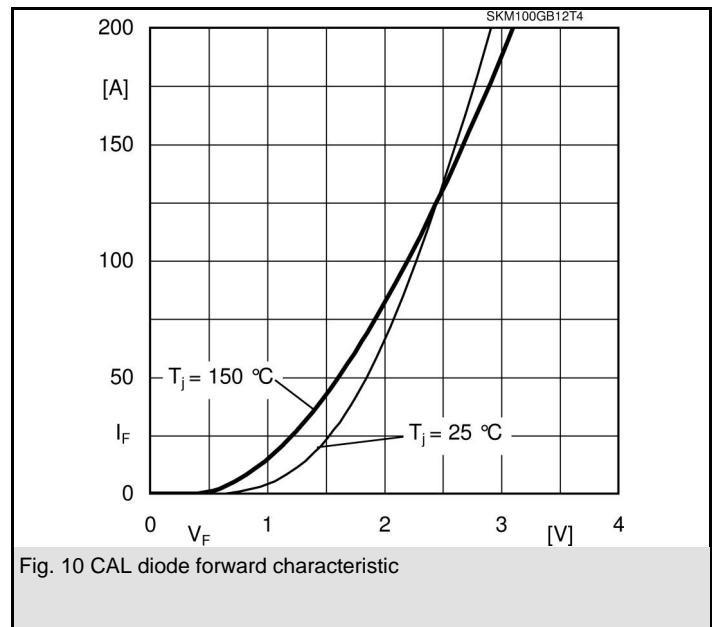


Fig. 10 CAL diode forward characteristic

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UL recognized file

CASED61

no. E 63 532

